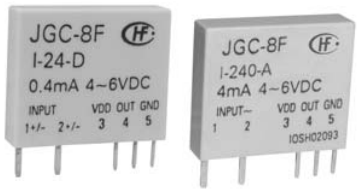
JGC-8F (lutput module) SOLID STATE RELAY



Features

- I/O modules for interface between CPU
- External input devices or loads.
- High isolation by employing photo-coupled devices (between input and output:2500V rms).
- Ultra slim and light weight: --size:20mmx17mmx5mm
- Printed circuit board mount

INPUT

Item		AC Input module		DC Input module	
		110VAC Type	240VAC Type	12/24VDC Type	
INPUT side	Input Voltage Range	80 to 132Vrms	160 to 265Vrms	9.6 to 28.8Vd.c.	
	Rating input Current	15mA max.		5mA max. (at 14.4Vd.c.)	10mA max. (at 28.8Vd.c.)
	Power Frequency Range	47 to 63Hz		--	--
	Must Operate Voltage	80Vrms	160Vrms	9.6Vd.c.	
	Must Release Voltage	30Vrms	40Vrms	5.0Vd.c.	
	Must Release Current	2mArms		1.5mA	
OUTPUT side	DC Supply Voltage(V_{DD})	4 to 6Vd.c.			
	Maximum Output Current	4mA@(V_{DD}=5V)			
	Output Logic	Operate with negative true logic(active low)			
	Maximum Operate Time	25ms		10ms	
	Maximum Release Time	30ms		10ms	
	Insulation Resistance	Minimum 1000MΩ(at 500Vd.c.)			
	Dielectric Strength	2500Vrms 1minute			
	Operating Temperature Range	-30˚C to +85 ˚C			
	Storage Temperature	-40˚C to +100 ˚C			
	Case Color	Yellow		White	
	Weight	3.5g max.			

ORDERING INFORMATION

Input module

JGC-8F / I 110 A XXX

Type

Module Type **I** : Input Module

Nominal Voltage (Input) **110**:110VAC **240**:240VAC **12**:12VAC **24**:24VAC

Input Voltage **A**: AC type **D**: DC type

Customer special request code

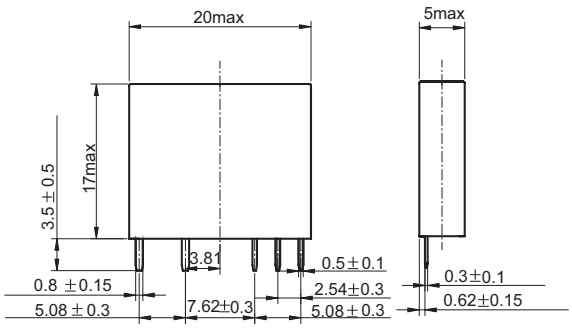
PRECAUTIONS

1. Soldering must be completed within 10 seconds at 260˚C or less or within 5 seconds at 350˚C or less.
2. The SSR case serves to dissipate heat. Install the relays so that they are adequately ventilated. If poor ventilation is unavoidable, reduce the load current by half.

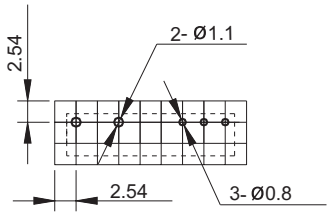
OUTLINE DIMENSIONS, WIRING DIAGRAM AND PC BOARD LAYOUT

input module

Dimensions

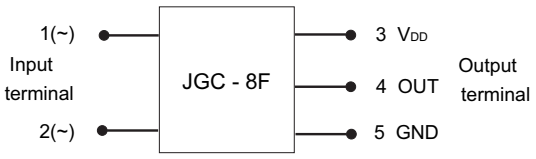


PCB mounting hole layout (BOTTOM VIEW)

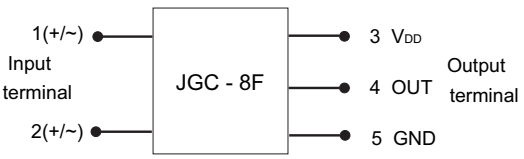


Wiring Diagram

JGC-8F/I ( )A type



JGC-8F/I ( )D type



CHARACTERISTICS CURVE

Figure 1 Maximum load current vs. ambient temperature